

# SOT909-2

plastic thermal enhanced very thin small outline package; no leads; 8 terminals

8 February 2016

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-229
Mounting method type	S (surface mount)
Issue date	25-1-2012

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.05	-	3.1	3.15	mm
E	package width		3.9	-	4	4.1	mm
A	seated height		0.8	-	0.85	1	mm
e	nominal pitch		-	-	0.8	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	8	-	

## 2. Package outline

Fig. 1. Package outline HVSON8 (SOT909-2)



### 3. Legal information

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